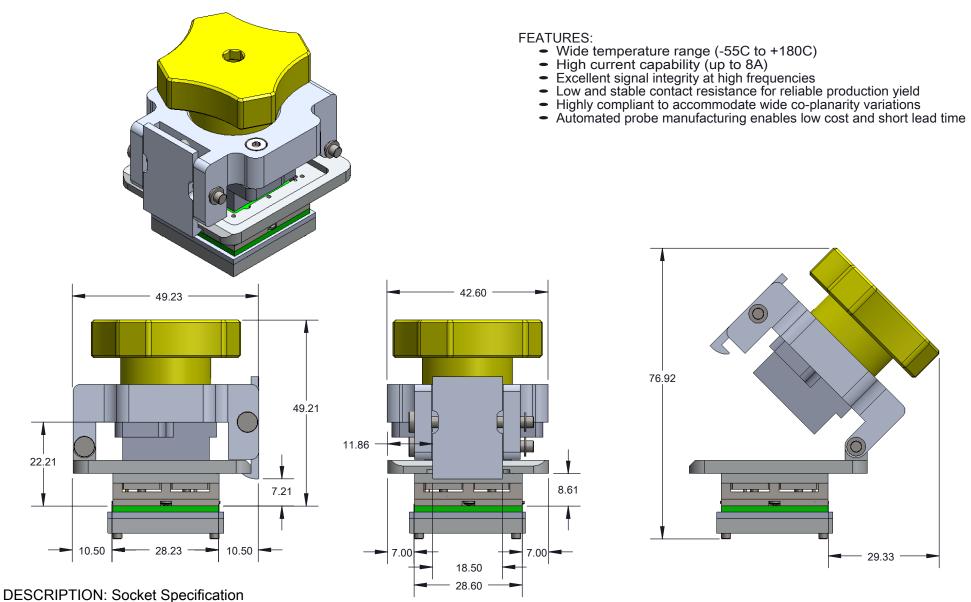
CBT-BGA DIRECT MOUNT, SOLDERLESS SOCKET FOR BURN-IN AND TEST APPLICATIONS

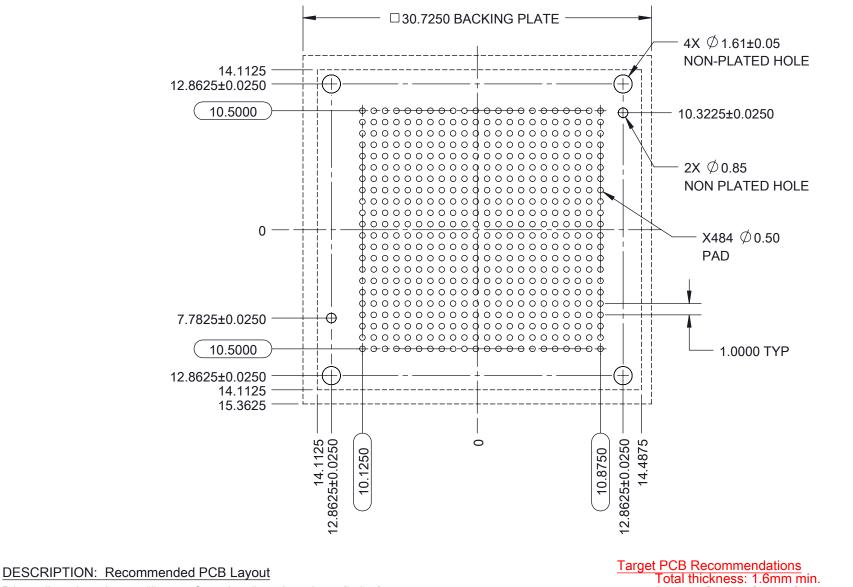


Primary dimension units are millimeters, Secondary dimension units are [inches].

<u>Tolerances:</u> diameters ± 0.03 mm [± 0.001 "], all other tolerances ± 0.13 mm [± 0.005 "] unless stated otherwise. Materials and specifications are subject to change without notice.

	CBT-BGA-6001	Drawing	STATUS: Released	SHEET: 1 of 4	REV. A
€	Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	WEIGHT: MATERIAL: FINISH:	DRAWN BY: M. Raske	SCALE: 1:1	
			File: CBT-BGA-6001	DATE: 10/19/2010	

Note: BGA pattern is not symmetrical with respect to the mounting holes



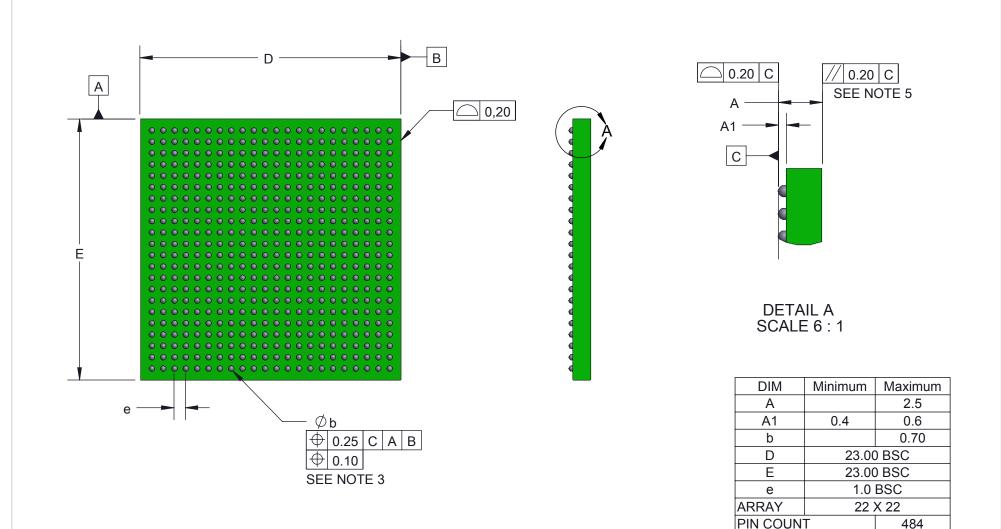
Primary dimension units are millimeters, Secondary dimension units are [inches]. Tolerances: diameters ±0.03mm [±0.001"],all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.



Plating: Gold or Solder finish

PCB Pad height: same or higher than solder mask

CBT-BGA-6001	Drawing	STATUS: Released	SHEET: 2 of 4	REV. A
Ironwood Electronics, Inc.	e: (800) 404-0204 MATERIAL:	DRAWN BY: M. Raske	SCALE: 2:1	
www.ironwoodelectronics.com		File: CBT-BGA-6001	DATE: 10/19/2010	



1. Dimensions are in millimeters.

Interpret dimensions and tolerances per ASME Y14.5M-1994.
Dimension b is measured at the maximum solder ball diameter, parallel to datum plane C.
Datum C (seating plane) is defined by the spherical crowns of the solder balls.

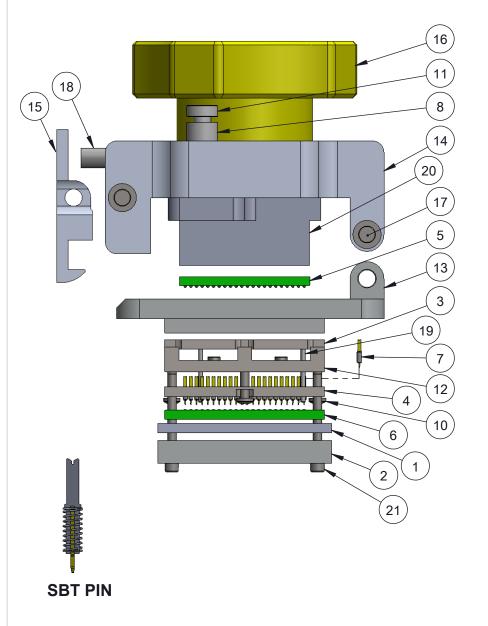
5. Parallelism measurement shall exclude any effect of mark on top surface of package.

DESCRIPTION: Compatible BGA

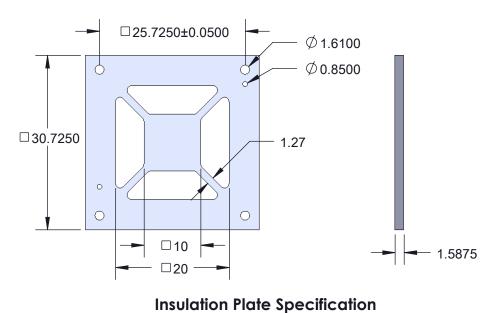
Primary dimension units are millimeters, Secondary dimension units are [inches].

Tolerances: diameters ±0.03mm [±0.001"],all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

	CBT-BGA-600	01 Drawing	STATUS: Released	SHEET: 3 of 4	REV. A
	Ironwood Electronics, Inc. Tele: (800) 404-0204 www.ironwoodelectronics.com	WEIGHT: MATERIAL: FINISH:	DRAWN BY: M. Raske	SCALE: 3:1	
À.			File: CBT-BGA-6001	DATE: 10/19/2010	



ITEM NO.	DESCRIPTION	Material
1	Insulation plate for 23x23mm IC	Material <not specified=""></not>
2	SBT/CBT NI PLT BACKING PLT 23MM	7075-T6, Plate (SS)
3	Floating Guide 23X23mm 1mm 22x22 arr	PEEK Ceramic filled
4	Bottom Guide 23X23mm 1mm 22x22 arr	PEEK Ceramic filled
5	BGA chip for 23x23mm 1mm, 22x22array	Material <not specified=""></not>
6	Target PCB for 23x23mm; 1mm, 22x22	Material <not specified=""></not>
7	Pogo Pin, 1mm Pitch SBT BGA pin	
8	Spring	
9	Floating Guide Spring	Alloy Steel (SS)
10	CR-PHMS 0.06-80x0.25x0.25-N	Material <not specified=""></not>
11	18-8 Stainless Steel: Socket Low Head Cap Screw	·
12	Middle Guide 23X23mm 1mm 22x22 arr CBT Socket Base clamshell 23mm Ni plt	PEEK Ceramic filled 7075-T6, Plate (SS)
13		
14	Socket Lid	7075-T6 Aluminum Alloy
15	Latch	7075-T6 Aluminum Alloy
16	Fluted Knob Compression Screw	7075-T6 Aluminum Alloy
17	Hinge and Snap Ring, 3mm OD X 30mm LG	Stainless Steel (ferritic)
18	Latch Spring	
19	1/32" DIA, 3/8" In Alignment Pin	Chrome Stainless Steel
20	CBT 23mm Compression plate Ni Plated	7075-T6 Aluminum Alloy
21	#0-80 X .625 LG, SOC HD CAP SCREW, ALLOY STL, BLK OXIDE	Alloy Steel



DESCRIPTION: Socket Assy, Insulation Plate

Primary dimension units are millimeters, Secondary dimension units are [inches].

<u>Tolerances:</u> diameters ± 0.03 mm [± 0.001 "], all other tolerances ± 0.13 mm [± 0.005 "] unless stated otherwise. Materials and specifications are subject to change without notice.

CBT-BGA-6001 Drawing			STATUS: Released	SHEET: 4 of 4	REV. A
	Ironwood Electronics, Inc. Tele: (800) 404-0204	WEIGHT: 0.00 MATERIAL: FINISH:	DRAWN BY: M. Raske	SCALE: 2:1	
	www.ironwoodelectronics.com		File: CBT-BGA-6001	DATE: 10/19/2010	